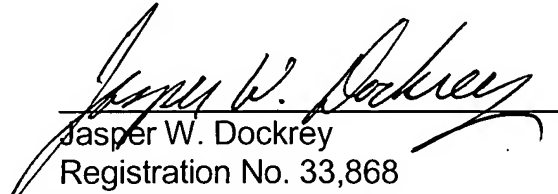


REMARKS

The applicants respectfully request entry of the amendment prior to commencing examination of the application.

Respectfully submitted,


Jasper W. Dockrey
Registration No. 33,868
Attorney for Applicants

BRINKS HOFER GILSON & LIONE
P.O. BOX 10395
CHICAGO, ILLINOIS 60610
(312) 321-4200

Amended Abstract

The invention concerns a method for making a thin film, which consists in creating a brittle zone embedded by implantation of a chemical species in a substrate (1), so as to be able subsequently to provoke a fracture of the substrate (1) along said brittle zone to separate therefrom said thin film (6). The invention is characterized in that the manufacturing method comprises in particular the following steps: a) a ~~main~~ first implantation in the substrate (1) at a ~~main~~ first depth (5) of a ~~main~~ first chemical species (4); b) implanting at least one second chemical species ~~secondary implantation~~ in the substrate (1), at a ~~secondary~~ second depth (3) different from said ~~main~~ first depth (5), and at a concentration higher than the concentration of the ~~main~~ first species (4), ~~of where the~~ at least a ~~secondary~~ second chemical species (2) is less efficient than the ~~main~~ first chemical species (4) for embrittling the substrate (1); c) ~~causing~~ diffusing at least part of said secondary species (2) ~~to migrate up~~ to the ~~proximity~~ vicinity of the ~~main~~ first depth (5); and d) ~~provoking~~ initiating a fracture along the ~~main~~ first depth (5). The invention also concerns the thin film obtained by the inventive method.